

Tool ID: 201
Tool Location: 107

Equipment Information Sheet
PT72 Etcher

Manager: Christopher Alpha
Backup: Tom Pennell

607-254-4913
607-254-4309

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- No unusual hazards during normal operation

USAGE RESTRICTIONS

- No buddy system restrictions imposed on normal operation

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- Maximum 2 hour block
- Maximum 2 reservations in advance at any time

MATERIALS COMPATIBILITY CATEGORY

Tool Category 4: Glass and Metal Categories	
Allowed	Not Allowed
Tool category 1/1E, 2, and 3 materials	
Silicon Based Substrates and Films	No CNF Class A metals
III/V compound Semiconductors	No Exposed CNF Group B metals- <i>metals can be buried/covered with staff approval</i>
Glass Substrates	Cannot be used as an etch stop
PECVD and ALD Films	
Buried Class B Metals with approval	
Organic/Bio Materials prepped w/o Salt Buffers	
Cured organics and baked Photoresist	No High Vapor pressure materials

High Vapor Pressure Metals and Compoundsare materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No gold or silver etching
- No high vapor pressure materials (lead indium, ITO)
- No microscope slides